



Dual N-Channel 40 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a	Q _g (Typ.)			
40	0.020 at V _{GS} = 10 V	9.2	4.9			
40	0.023 at V _{GS} = 4.5 V	8.6	4.5			

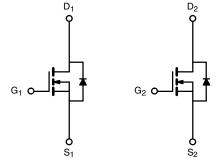
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_q and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



APPLICATIONS

- CCFL Inverter
- DC/DC Converter
- HDD



N-Channel MOSFET

N-Channel MOSFET

		SO-8		
S ₁	1		8	D ₁
G_1	2		7	D_1
S_2	3		6	D_2
G_2	4		5	D_2
	ı	Top View		

Ordering Information: Si4288DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS (T	4 = 25 C, unless office				
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V_{DS}	40	V	
Gate-Source Voltage		V_{GS}	± 20		
	T _C = 25 °C		9.2		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C	L	7.4	Ī	
Continuous Diain Current (1) = 130°C)	T _A = 25 °C	I _D	7.4 ^{b, c}		
	T _A = 70 °C		5.9 ^{b, c}	1	
Pulsed Drain Current (10 µs Pulse Width)		I _{DM}	50	A	
Occurs Busin Occurs I Bis do Occurs I	T _C = 25 °C	T _C = 25 °C	2.6	A	
Source-Drain Current Diode Current	T _A = 25 °C	'S	1.6 ^{b, c}	1	
Pulsed Source-Drain Current	I _{SM}	50			
Single Pulse Avalanche Current Single Pulse Avalanche Energy L = 0.1 mH		I _{AS}	10		
		E _{AS}	5		
	T _C = 25 °C		3.1		
Maximum Power Dissipation	T _C = 70 °C	P _D	2	w	
Maximum Fower Dissipation	T _A = 25 °C	' D	2 ^{b, c}	T **	
	T _A = 70 °C		1.28 ^{b, c}	1	
Operating Junction and Storage Temperature Range	T _J , T _{stq}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Тур.	Max.	Unit			
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	49	62.5	°C/W		
Maximum Junction-to-Foot (Drain)	Steady-State	R _{thJF}	30	40] 5/**		

Notes:

- a. Based on T_C = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under steady state conditions is 120 $^{\circ}\text{C/W}.$

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Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static	-				l		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	40			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J. 050A		49		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 5.2			
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2		2.5	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			100	nA	
Zone Cote Valta de Busin Comment		V _{DS} = 40 V, V _{GS} = 0 V	1 10		1	μА	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10		
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	20			Α	
	В	V _{GS} = 10 V, I _D = 10 A		0.0165	0.0200	Ω	
Drain-Source On-State Resistance ^b	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 7 \text{ A}$		0.019	0.023		
Forward Transconductance ^b	g _{fs}	V _{DS} = 15 V, I _D = 10 A		35		S	
Dynamic ^a				•	•		
Input Capacitance	C _{iss}			580			
Output Capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, I_{D} = 1 \text{ MHz}$		100		pF	
Reverse Transfer Capacitance	C _{rss}			42			
Tabel Oaks Observe	Qg	V _{DS} = 20 V, V _{GS} = 10 V, I _D = 10 A		10	15	nC	
Total Gate Charge				4.9	7.4		
Gate-Source Charge	Q_{gs}	$V_{DS} = 20 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$		1.5			
Gate-Drain Charge	Q _{gd}			1.5			
Gate Resistance	R_{g}	f = 1 MHz	0.6	2.7	5.4	Ω	
Turn-On Delay Time	t _{d(on)}			7	14		
Rise Time	t _r	$V_{DD} = 20 \text{ V}, R_L = 2 \Omega$		9	18		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		16	32		
Fall Time	t _f			8	16		
Turn-On Delay Time	t _{d(on)}			12	24	ns	
Rise Time	t _r	$V_{DD} = 20 \text{ V}, R_L = 2 \Omega$		10	20		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		13	26		
Fall Time	t _f			8	16		
Drain-Source Body Diode Characterist	cs			•	•		
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			2.6		
Pulse Diode Forward Current ^a	I _{SM}				50	_ A	
Body Diode Voltage	V _{SD}	I _S = 3 A		0.77	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			15	30	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			7.5	15	nC	
Reverse Recovery Fall Time	t _a	$I_F = 5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 °C$		9			
Reverse Recovery Rise Time	t _b			6		ns	

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

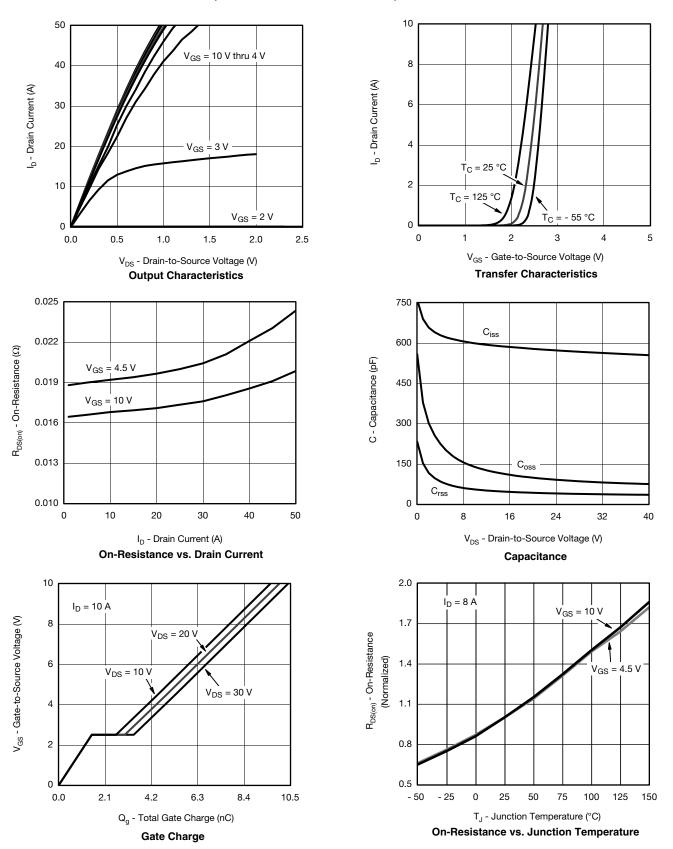
a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$



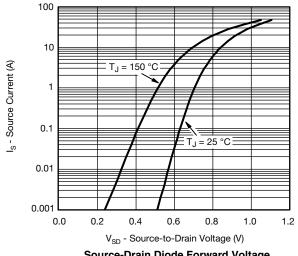


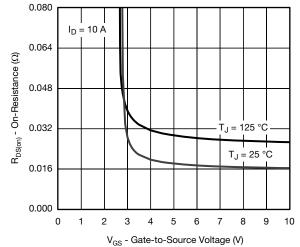
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



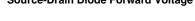
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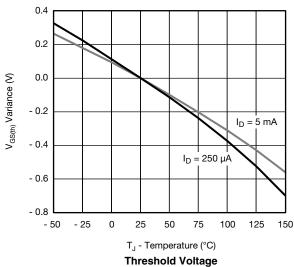
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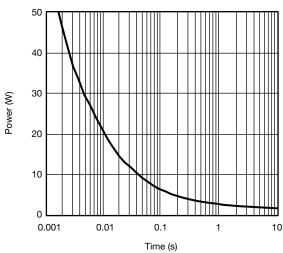


Source-Drain Diode Forward Voltage

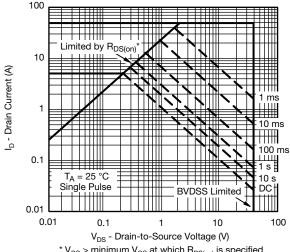




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

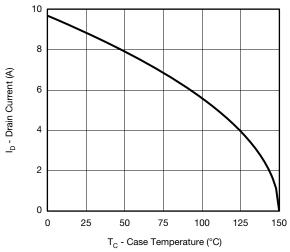


* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

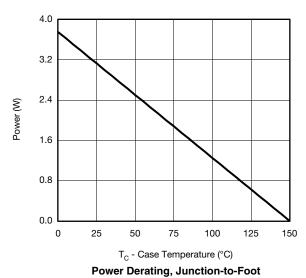
Safe Operating Area

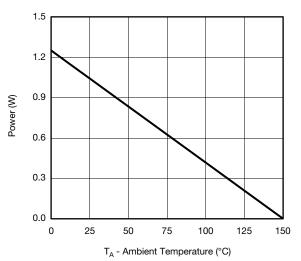


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating*





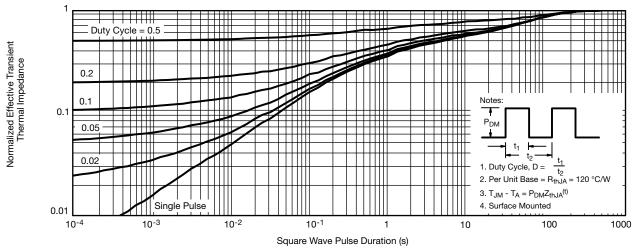
Power Derating, Junction-to-Ambient

 $^{^{\}star}$ The power dissipation P_D is based on T_{J(max)} = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

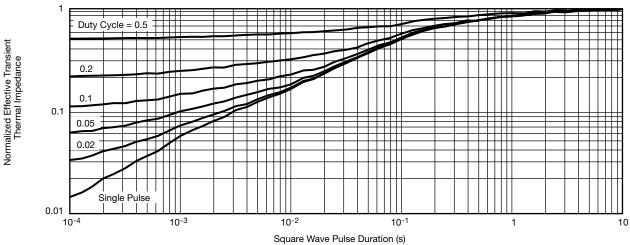
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIM	IETERS	INCHES			
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
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RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index

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